substance deposited on the light emitting device is very small, quantity of the fluorescent substance (namely thickness of the coating layer) can be controlled to be uniform. As a result, light emitting apparatuses having less variability can be manufactured.

[0054]

Brief Description of the Drawings

The above and other objectives and features of the present invention will become more apparent from description of a preferred embodiment thereof with reference to the accompanying drawings, throughout which like parts are designated by like reference numerals, and wherein:

Fig. 1 is a schematic top view of a light emitting apparatus according to one embodiment of the present invention.

Fig. 2 is a schematic sectional view of the light emitting apparatus shown in Fig. 1.

Fig. 3 is a schematic sectional view of a light emitting apparatus according to another embodiment of the present invention.

Fig. 4 is a diagram schematically showing a process of spraying a coating solution in the form of spiral mist stream to the light emitting device.

Fig. 5 is a schematic diagram showing the constitution of an apparatus for spraying the coating solution.

Figs. 6A to 6E ~~Figs. 6A to 6D~~ are sectional views showing a process of manufacturing the light emitting device having a semiconductor layer formed on a support substrate (metal substrate). mg 10.10.07

Fig. 7 is a sectional view showing an example of the structure of the light emitting device having a semiconductor layer formed on a support substrate (metal substrate).